

CSD04060-Silicon Carbide Schottky Diode

ZERO RECOVERY® RECTIFIER

$$\mathbf{V}_{\mathbf{RRM}}$$
 = 600 V
 $\mathbf{I}_{\mathbf{F}(\mathbf{AVG})}$ = 4 A
 $\mathbf{Q}_{\mathbf{c}}$ = 9 nC

Features

- 600-Volt Schottky Rectifier
- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Switching
- Positive Temperature Coefficient on V_F

Benefits

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

Applications

- Switch Mode Power Supplies
- Power Factor Correction
- Typical PFC P_{out}: 400W-800W
 Motor Drives
 - Typical Power : 0.5HP-2HP

Package





Part Number	Package	Marking
CSD04060A	TO-220-2	CSD04060
CSD04060E	TO-252-2	CSD04060

Maximum Ratings

Symbol	Parameter	Value	Unit	Test Conditions	Note
V _{RRM}	Repetitive Peak Reverse Voltage	600	V		
V _{RSM}	Surge Peak Reverse Voltage	600	V		
V _{DC}	DC Blocking Voltage	600	V		
$I_{\text{F}(\text{AVG})}$	Average Forward Current	4 7	А	T _c =150°C T _c =125°C	
$I_{\rm F(PEAK)}$	Peak Forward Current	10	А	T _c =125°, T _{REP} <1 mS, Duty=0.5	
I _{frm}	Repetitive Peak Forward Surge Current	17.5 12.5	А	$T_c=25$ °C, $t_p=10$ ms, Half Sine Wave $T_c=125$ °C, $t_p=10$ ms, Half Sine Wave	
$\mathbf{I}_{\mathrm{FSM}}$	Non-Repetitive Peak Forward Surge Current	38	А	$T_c=25^{\circ}C$, $t_p=1.5$ ms, Half Sine Wave	
\mathbf{I}_{FSM}	Non-Repetitive Peak Forward Surge Current	110	А	$T_c=25^{\circ}C$, $t_p=10 \ \mu s$, Pulse	
P_{tot}	Power Dissipation	62.5 20.8	W	T _c =25°C T _c =125°C	
$T_{_{\mathrm{J}}}$, $T_{_{\mathrm{stg}}}$	Operating Junction and Storage Temperature	-55 to +175	°C		
	TO-220 Mounting Torque	1 8.8	Nm lbf-in	M3 Screw 6-32 Screw	



Electrical Characteristics

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
V _F	Forward Voltage	1.5 2.0	1.8 2.4	V	$I_{F} = 4 A T_{J} = 25^{\circ}C$ $I_{F} = 4 A T_{J} = 175^{\circ}C$	
I _R	Reverse Current	25 50	200 1000	μA	$V_{R} = 600 V T_{J} = 25^{\circ}C$ $V_{R} = 600 V T_{J} = 175^{\circ}C$	
Q _c	Total Capacitive Charge	9		nC	$V_{R} = 600 \text{ V}, I_{F} = 4\text{A}$ $di/dt = 500 \text{ A}/\mu\text{s}$ $T_{J} = 25^{\circ}\text{C}$	
С	Total Capacitance	220 26 20		pF	$ \begin{array}{l} V_{_R} = 0 \ V, \ T_{_J} = 25 \ ^\circ C, \ f = 1 \ MHz \\ V_{_R} = 200 \ V, \ T_{_J} = 25 \ ^\circ C, \ f = 1 \ MHz \\ V_{_R} = 400 \ V, \ T_{_J} = 25 \ ^\circ C, \ f = 1 \ MHz \end{array} $	

Note:

1. This is a majority carrier diode, so there is no reverse recovery charge.

Thermal Characteristics

Symbol	Parameter	Тур.	Unit
R _{ejc}	Thermal Resistance from Junction to Case	2.4	°C/W

Typical Performance

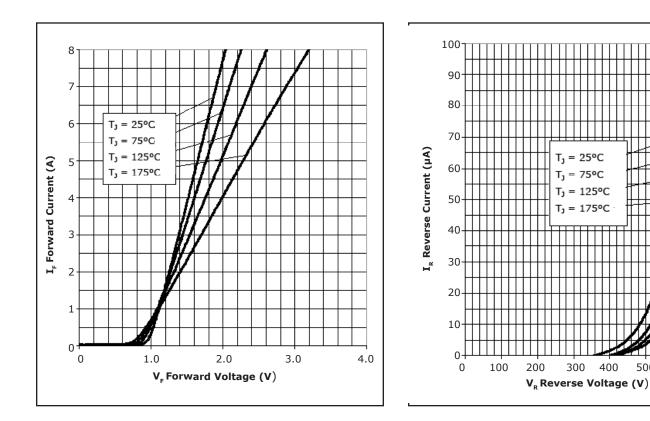
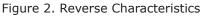


Figure 1. Forward Characteristics



400

500

600

700



Typical Performance

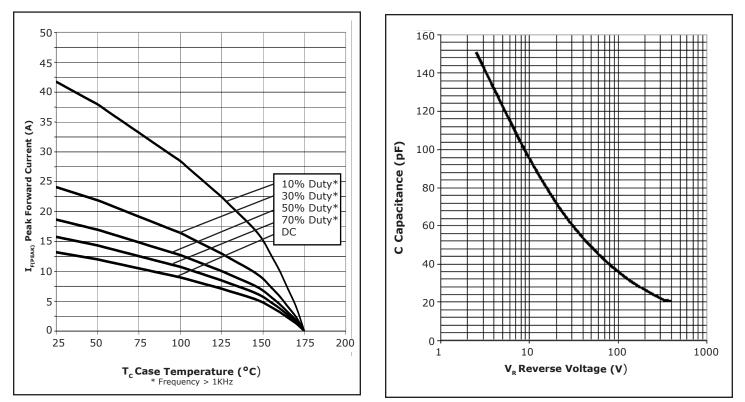


Figure 3. Current Derating

Figure 4. Capacitance vs. Reverse Voltage

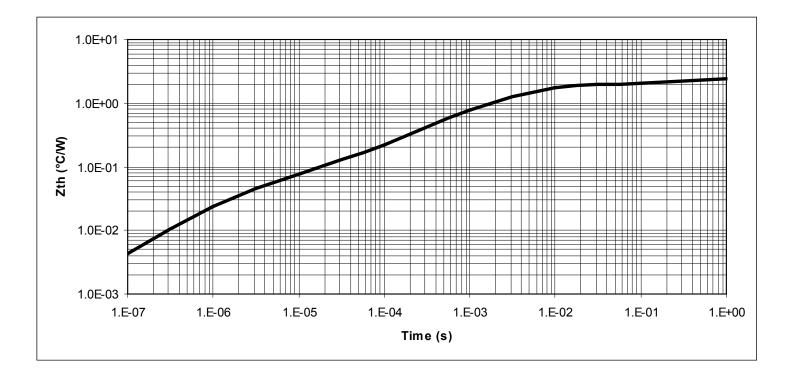


Figure 5. Transient Thermal Impedance

3



Typical Performance

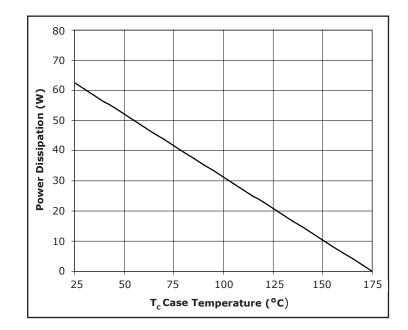
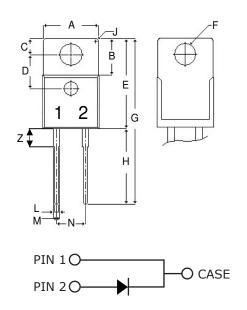


Figure 6. Power Derating



Package Dimensions

Package TO-220-2



++Q

=‡U

٧

W

m

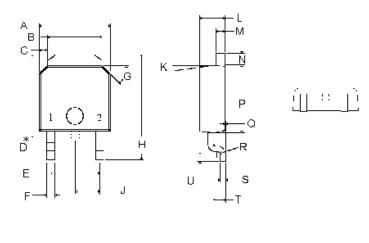
Y =

S⁺

T₽



Package TO-252-2





	POS	Inc	hes	Millimeters		
	POS	Min	Max	Min	Max	
	А	.381	.410	9.677	10.414	
	В	.235	.255	5.969	6.477	
	С	.100	.120	2.540	3.048	
	D	.223	.337	5.664	8.560	
	E	.590	.615	14.986	15.621	
	F	.143	.153	3.632	3.886	
┉┤	G	1.105	1.147	28.067	29.134	
	Н	.500	.550	12.700	13.970	
135	J	R 0.197		R 0.197		
	L	.025	.036	.635	.914	
	М	.045	.055	1.143	1.397	
	Ν	.195	.205	4.953	5.207	
	Р	.165	.185	4.191	4.699	
	Q	.048	.054	1.219	1.372	
	S	3°	6°	3°	6°	
	Т	3°	6°	3°	6°	
	U	3°	6°	3°	6°	
	V	.094	.110	2.388	2.794	
	W	.014	.025	.356	.635	
	Х	3°	5.5°	3°	5.5°	
	Y	.385	.410	9.779	10.414	
	z	.130	.150	3.302	3.810	

NOTE:

1. Dimension L, M, W apply for Solder Dip Finish

POS	Inc	hes	Millimeters		
P05	Min	Мах	Min	Мах	
A	.255	.265	6.477	6.731	
В	.197	.205	5.004	5.207	
С	.027	.033	.686	.838	
D*	.270	.322	6.858	8.179	
E	.178	.182	4.521	4.623	
F	.025	.035	.635	.889	
G	44°	46°	44°	46°	
Н	.382	.397	9.703	10.084	
J	.090	ТҮР	2.286 TYP		
К	6°	8°	6°	8°	
L	.086	.094	2.184	2.388	
М	.030	.034	.762	.864	
N	.040	.044	1.016	1.118	
Р	.235	.245	5.969	6.223	
Q	0.00	.004	0.00	.102	
R	R0.01 TYP		R0.31 TYP		
S	.017	.023	.428	.588	
Т	.040	.044	1.016	1.118	
U	.021	.027	.534	1.118	

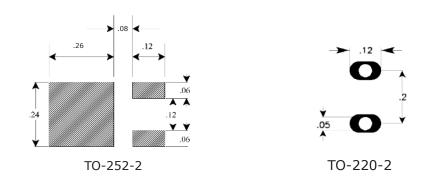
Note:

* Tab "D" may not be present

5

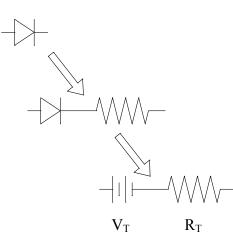


Recommended Solder Pad Layout



Part Number	Package	Marking
CSD04060A	TO-220-2	CSD04060
CSD04060E	TO-252-2	CSD04060

Diode Model



 $Vf_T = V_T + If^*R_T$

 $\begin{array}{l} V_{T^{=}} 0.965 + (T_{j} * \text{--} 1.3 * 10^{\text{--}3}) \\ R_{T^{=}} 0.096 + (T_{j} * 1.06 * 10^{\text{--}3}) \end{array}$

Note: T_i = Diode Junction Temperature In Degrees Celcius

"The levels of environmentally sensitive, persistent biologically toxic (PBT), persistent organic pollutants (POP), or otherwise restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2002/95/EC on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS), as amended through April 21, 2006. This part number was released previously with Sn/Pb solder plating as a standard industry finish. For more information please contact power_sales@cree.com "

This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, air traffic control systems, or weapons systems.

Cree, Inc. 4600 Silicon Drive Durham, NC 27703 USA Tel: +1.919.313.5451 Fax: +1.919.313.5451 www.cree.com/power

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